

NTBG015N065SC1 Datasheet



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DiGi Electronics Part Number NTBG015N065SC1-DG

Manufacturer onsemi

Manufacturer Product Number NTBG015N065SC1

Description SILICON CARBIDE MOSFET, NCHANNEL

Detailed Description N-Channel 650 V 145A (Tc) 500W (Tc) Surface Moun

t D2PAK-7



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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
NTBG015N065SC1	onsemi
Series:	Product Status:
	Active
FET Type:	Technology:
N-Channel	SiCFET (Silicon Carbide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
650 V	145A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ ld, Vgs:
15V, 18V	18mOhm @ 75A, 18V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
4.3V @ 25mA	283 nC @ 18 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
+22V, -8V	4689 pF @ 325 V
FET Feature:	Power Dissipation (Max):
	500W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 175°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
D2PAK-7	TO-263-8, D2PAK (7 Leads + Tab), TO-263CA

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

8541.29.0095

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Silicon Carbide (SiC)
MOSFET - EliteSiC,
12 mohm, 650 V, M2,

NTBG015N065SC1

Features

- Typ. $R_{DS(on)} = 12 \text{ m}\Omega$ @ $V_{GS} = 18 \text{ V}$ Typ. $R_{DS(on)} = 15 \text{ m}\Omega$ @ $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge $(Q_{G(tot)} = 283 \text{ nC})$
- Low Effective Output Capacitance (Coss = 424 pF)
- 100% Avalanche Tested

D2PAK-7L

- $T_I = 175^{\circ}C$
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

Typical Applications

- SMPS (Switching Mode Power Supplies)
- Solar Inverters
- UPS (Uninterruptable Power Supplies)
- Energy Storages

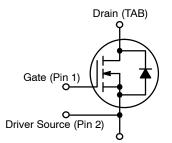
MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	650	V
Gate-to-Source Voltage	ge		V_{GS}	-8/+22	V
Recommended Operatives of Gate – Source		T _C < 175°C	V_{GSop}	-5/+18	>
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	T _C = 25°C	I _D	145	Α
Power Dissipation $R_{\theta JC}$ (Note 2)			P _D	500	W
Continuous Drain Current R _{0JA} (Notes 1, 2)	Steady State	T _C = 100°C	Ι _D	103	Α
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)			P _D	250	W
Pulsed Drain Current (Note 3)	T _C = 25°C	I _{DM}	422	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	111	Α
Single Pulse Drain-to-Source Avalanche Energy (I _L = 13 A _{pk} , L = 1 mH) (Note 4)			E _{AS}	84	mJ
Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds			TL	245	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface mounted on a FR-4 board using1 in2 pad of 2 oz copper.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. Repetitive rating, limited by max junction temperature.
- 4. E_{AS} of 84 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 13 A, V_{DD} = 50 V, V_{GS} = 18 V.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	18 mΩ @ 18 V	145 A



Power Source (Pins 3, 4, 5, 6, 7)

N-CHANNEL MOSFET



D2PAK-7L CASE 418BJ

MARKING DIAGRAM

BG015N 065SC1 AYWWZZ

BG015N065SC1 = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping [†]
NTBG015N065SC1	D2PAK-7L	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <u>BRD8011/D</u>.

THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-to-Case (Note 2)	$R_{ heta JC}$	0.3	°C/W
Thermal Resistance Junction-to-Ambient (Notes 1, 2)	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS	-		-	-	-	-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	650			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 20 mA, refer to 25°C		0.12		V/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V}, \qquad T_J = 25^{\circ}\text{C}$			10	μΑ
		V _{DS} = 650 V T _J = 175°C			1	mA
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +22/-8 V, V _{DS} = 0 V			250	nA
ON CHARACTERISTICS	•	•		•	•	•
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 25$ mA	1.8	2.8	4.3	V
Recommended Gate Voltage	V_{GOP}		-5		+18	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 75 A, T _J = 25°C		15		mΩ
		V _{GS} = 18 V, I _D = 75 A, T _J = 25°C		12	18	
		V _{GS} = 18 V, I _D = 75 A, T _J = 175°C		16		
Forward Transconductance	9FS	V _{DS} = 10 V, I _D = 75 A		42		S
CHARGES, CAPACITANCES & GATE RES	SISTANCE		-	-		
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz,		4689		pF
Output Capacitance	Coss	V _{DS} = 325 V		424		
Reverse Transfer Capacitance	C _{RSS}			37		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/18 \text{ V}, V_{DS} = 520 \text{ V},$		283		nC
Gate-to-Source Charge	Q _{GS}	I _D = 75 A		72		
Gate-to-Drain Charge	Q_{GD}			64		
Gate-Resistance	R_{G}	f = 1 MHz		1.6		Ω
SWITCHING CHARACTERISTICS			1			
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = -5/18 \text{ V}, V_{DS} = 400 \text{ V},$		23		ns
Rise Time	t _r	$I_D = 75 \text{ A}, R_G = 2.2 \Omega,$ Inductive Load		26		
Turn-Off Delay Time	t _{d(OFF)}			49		
Fall Time	t _f			9.6		
Turn-On Switching Loss	E _{ON}			167		μJ
Turn-Off Switching Loss	E _{OFF}			276		
Total Switching Loss	E _{TOT}			443		
DRAIN-SOURCE DIODE CHARACTERIST	ics	•	•	•	•	•
Continuous Drain-Source Diode Forward Current	I _{SD}	$V_{GS} = -5 \text{ V}, T_J = 25^{\circ}\text{C}$			111	Α
Pulsed Drain-Source Diode Forward Current (Note 3)	I _{SDM}	V _{GS} = -5 V, T _J = 25°C			422	Α
Forward Diode Voltage	V _{SD}	V _{GS} = -5 V, I _{SD} = 75 A, T _J = 25°C		4.8		V

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)(continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit		
DRAIN-SOURCE DIODE CHARACTERISTICS								
Reverse Recovery Time	t _{RR}	$V_{GS} = -5/18 \text{ V}, I_{SD} = 75 \text{ A},$		28		ns		
Reverse Recovery Charge	Q _{RR}	dl _S /dt = 1000 A/μs		234		nC		
Reverse Recovery Energy	E _{REC}			23		μJ		
Peak Reverse Recovery Current	I _{RRM}			16		Α		
Charge Time	Ta			17		ns		
Discharge Time	Tb			11		ns		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

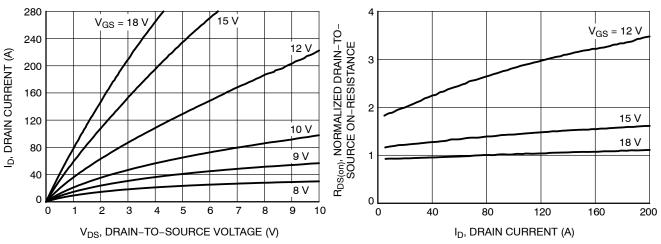


Figure 1. On-Region Characteristics

Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

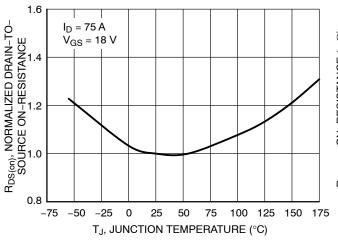


Figure 3. On–Resistance Variation with Temperature

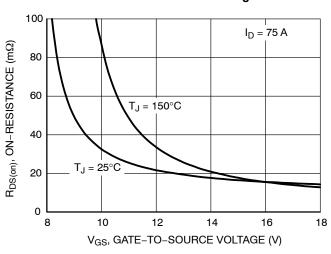


Figure 4. On-Resistance vs. Gate-to-Source Voltage

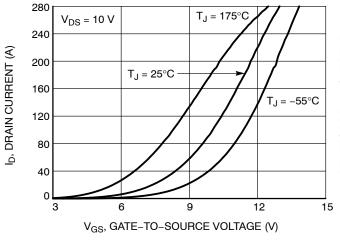


Figure 5. Transfer Characteristics

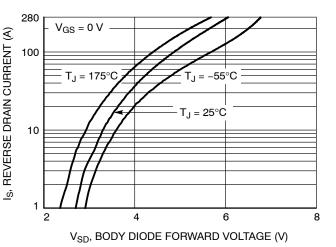


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS (continued)

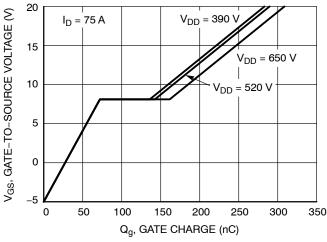


Figure 7. Gate-to-Source Voltage vs. Total Charge

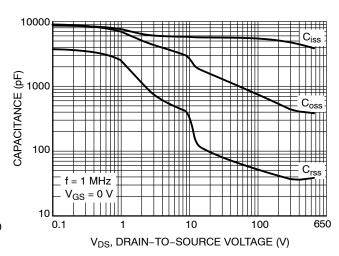


Figure 8. Capacitance vs. Drain-to-Source Voltage

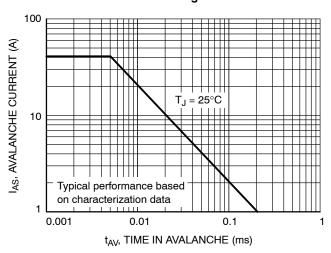


Figure 9. Unclamped Inductive Switching Capability

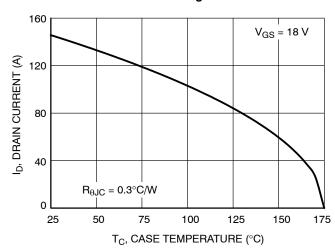


Figure 10. Maximum Continuous Drain **Current vs. Case Temperature**

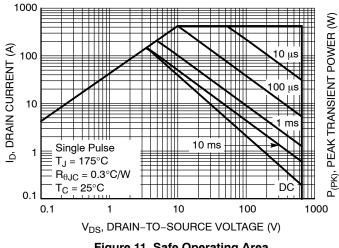


Figure 11. Safe Operating Area

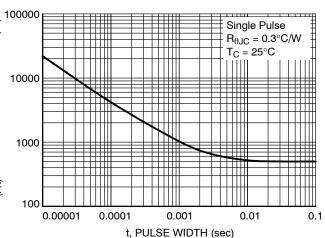


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

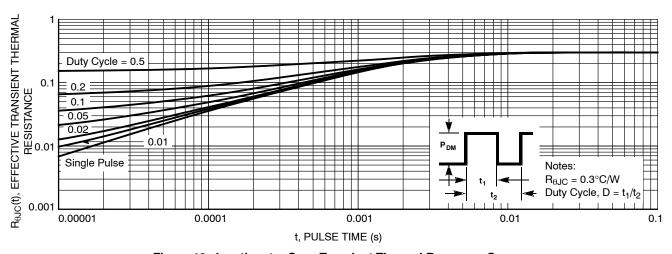


Figure 13. Junction-to-Case Transient Thermal Response Curve



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3.20 MIN

| B | A |M)

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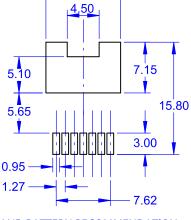
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

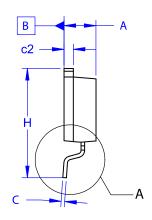
D²PAK7 (TO-263-7L HV) CASE 418BJ **ISSUE B**

10.50 4.50 5.10 7.15 15.80 5.65 3.00

LAND PATTERN RECOMMENDATION



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DATE 16 AUG 2019

NOTES:

A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.

OUT OF JEDEC STANDARD VALUE.
D. DIMENSION AND TOLERANCE AS PER ASME
Y14.5-2009.

E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

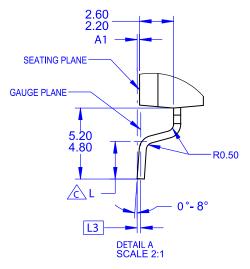
DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.30	4.50	4.70	
A 1	0.00	0.10	0.20	
b2	0.60	0.70	0.80	
b	0.51	0.60	0.70	
С	0.40	0.50	0.60	
c2	1.20	1.30	1.40	
D	9.00	9.20	9.40	
D1	6.15	6.80	7.15	
Е	9.70	9.90	10.20	
E1	7.15	7.65	8.15	
е	~	1.27	~	
Н	15.10	15.40	15.70	
L	2.44	2.64	2.84	
L1	1.00	1.20	1.40	
L3	~	0.25	~	
aaa	~	~	0.25	

GENERIC MARKING DIAGRAM* XXXXXXXX **AYWWG**

XXXX = Specific Device Code = Assembly Location Α

Υ = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.



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DESCRIPTION:	D ² PAK7 (TO-263-7L HV)		PAGE 1 OF 1	

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